

Title (en)

METHOD OF MAKING A LAMINATE COMPRISING A CONDUCTIVE POLYMER COMPOSITION

Title (de)

VERFAHREN ZUM HERSTELLEN VON LAMINATEN AUS LEITENDEN POLYMERZUSAMMENSETZUNGEN

Title (fr)

PROCEDE DE PRODUCTION D'UN STRATIFIE COMPRENANT UNE COMPOSITION POLYMERE CONDUCTRICE

Publication

EP 0918638 A1 19990602 (EN)

Application

EP 97934350 A 19970730

Priority

- US 9713419 W 19970730
- US 69175196 A 19960801

Abstract (en)

[origin: WO9805503A1] A method of making a laminate from a conductive polymer composition in which a particulate filler is dispersed in a polymeric component. The method comprises the following steps conducted sequentially in a single continuous procedure: (A) loading the polymeric component and the conductive filler into a mixing apparatus; (B) mixing the polymeric component and the conductive filler to form a molten mixture; (C) transporting the mixture from the mixing apparatus through a die; (D) forming a polymeric sheet; and (E) attaching metal foil to a least one side of the sheet to form a laminate. The laminate can be used to prepare circuit protection devices or heaters.

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IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 9805503A1

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